

Specification HW941A

SSC		CUSTOMER
Drawn	Approval	Approval

Rev. 04 December 2008 www.ZLED.com



CONTENTS

- 1. Full code of HIGH FLUX LED series
- 2. Feature & Application
- 3. Absolute Maximum Ratings
- 4. Electro Characteristics
- 5. Outline Dimension
- 6. Optical characteristics
- 7. Color & Binning
- 8. Rank of HW941A
- 9. Packing
- 10. Soldering
- 11. Precaution for use
- 12. Reliability Test Item and Condition

Rev. 04 December 2008 www.ZLED.com



1. Full Code of HIGH FLUX LED Series

Full code form : $X_1^{} \, X_2^{} \, X_3^{} \, X_4^{} \, X_5^{} \, X_6^{} \, X_7^{} X_8^{} \, \,$ - $X_{10}^{} X_{11}^{}$

1. Part Number

- X₁ : Model
- X₂: Number of Die *1
- X₃ : Color
- X₄ : Lens Shape
- X₅ : Directivity
- X₆: Revision Symbol
- X7 : High Reliability *2
- X₈: Surface coloring & Diffusion *3
- *1, 2, 3 are added to the Product Type only in necessary cases.

2. Internal Number

- X₁₀
- X₁₁

3. Sticker Diagram on Box & Plastic Tube

Hc14



LOT NO. 20XX.XX.XX







Rev. 04 December 2008 www.ZLED.com

HW941A

Description

This revolutionary package design allows the lighting designer to reduce the number of LEDs required and provide a more uniform and unique illuminated appearance than with other LED solutions.

This package LEDs are designed for high current operation and high flux output application. But the package's design features better thermal management characteristics than other LED solutions. Because of these advantages, this product have many applications. Such as automotive tail, stop and turn signal lamps, and electronic signs etc.





HW941A

Features

- High flux output and high luminance
- Designed for high current operation
- Uniform color
- Low profile and low thermal resistance
- Packaged in tubes for use with automatic insertion equipment

Applications

- Automotive exterior lighting
- Electronic signs and signals
- Channel letter / lighting
- Decorative lighting
- Specialty Lighting

Rev. 00 October 2008 www.ZLED.com

3. Absolute maximum ratings

Parameter	Symbol	Value	Unit
DC Forward Current	I _F	30	mA
Forward Peak Pulse Current	Ι _{FP} ^[1]	100	mA
Reverse Voltage	V _R	5	V
Power Dissipation	P _D	120	mW
Operating Temperature	T _{opr}	-40 ~ 100	°C
Storage Temperature	T _{stg}	-40 ~ 100	°C
Solder Temperature	Ts	260°C for 5second [2]	°C

[1] $t \le 0.1$ ms, D = 1/10

[2] No closer than stopper.

4. Electric & Optical characteristics

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Luminous Flux [3]	Φ_V	IF=30mA	3.4	6.0	-	lm
Chromaticity Coordinate ^[4]	Х, у	IF=30mA	x=	0.31, y=0	.31	-
Forward Voltage ^[5]	V _F	IF=30mA	-	3.4	4.0	V
View Angle	2 <i>θ</i> ½	IF=30mA		130		Deg.
Thermal Resistance	$R heta_{J-P}$	IF=30mA		130		°C /W
Reverse Current	I _R	Vr=5V	-	-	5	μA

[3] SSC maintains a tolerance of $\pm 10\%$ on flux and power measurements.

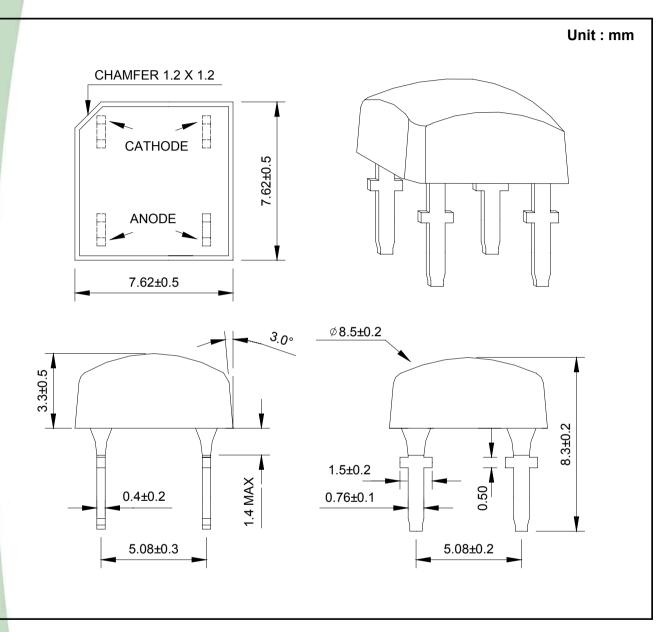
[4] Correlated Color Temperature is derived from the CIE 1931 Chromaticity diagram. Color Coordinates Measurement allowance is \pm 0.01

[5] A tolerance of $\pm 0.05 V$ on forward voltage measurements.

[Note] All measurements were made under the standardized environment of SSC.

Rev. 04 December 2008 www.ZLED.com





Notes : Protruded epoxy is 1.0mm maximum.

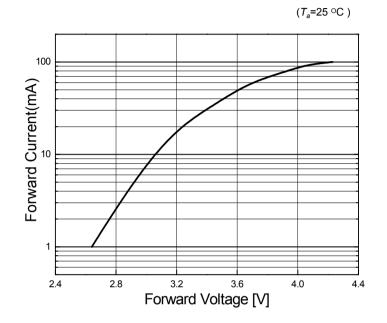
Rev. 04 December 2008 www.ZLED.com

SEOUL SEMICONDUCTOR

SEOUL

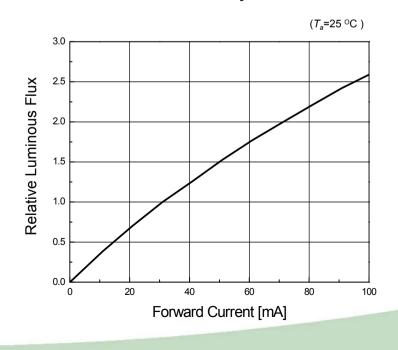


6. Optical characteristics



Forward Current vs. Forward Voltage

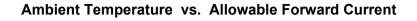
Relative Luminous Intensity vs Forward Current

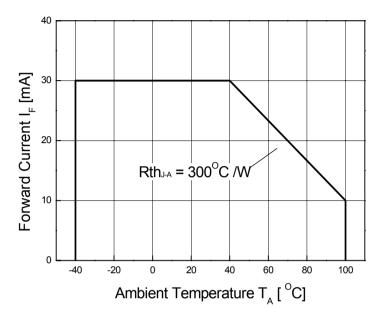


Rev. 04 December 2008 www.ZLED.com



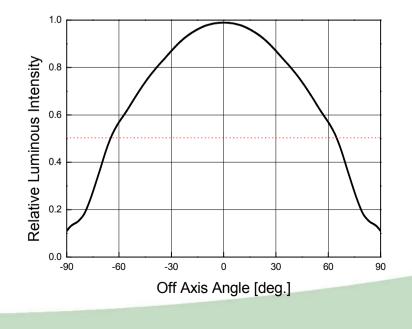
6. Optical characteristics





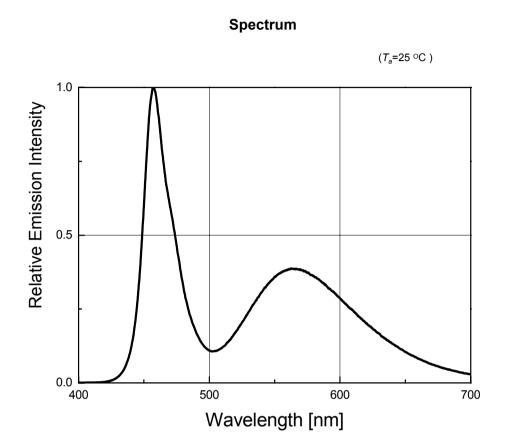
Radiation Diagram

(*T_a*=25 °C)



Rev. 04 December 2008 www.ZLED.com





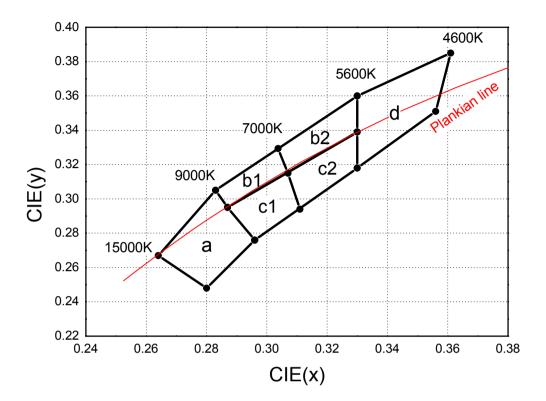
Rev. 04 December 2008 www.ZLED.com

SEOUL SEMICONDUCTOR

SEOUL



7. Color & Binning



	Rank a			
х	0.264	0.280	0.296	0.283
у	0.267	0.248	0.276	0.305
	Rank b2			
x	0.307	0.304	0.330	0.330
	0.315	0.330	0.360	0.339

	Rank c2			
x	0.311	0.307	0.330	0.330
У	0.294	0.315	0.339	0.318

	Rank b1			
х	0.287	0.283	0.304	0.307
у	0.295	0.305	0.330	0.315

	Rank c1			
х	0.296	0.287	0.307	0.311
у	0.276	0.295	0.315	0.294

	Rank d			
х	0.330	0.330	0.356	0.361
у	0.360	0.318	0.351	0.385

Note : Color Coordinates Measurement allowance is $\pm \mbox{ 0.01}$

Rev. 04 December 2008 www.ZLED.com

8. Rank of HW941A

Bin Code				
Luminous Flux	CIE	Forward Voltage		
Н	c1	4		

SEOUL

Luminous Flux (lm) @ <i>I_F</i> = 30mA					
Bin Code	Min.	Max.			
G	3.4	4.4			
н	4.4	5.8			
J	5.8	7.6			
К	7.6	10.0			

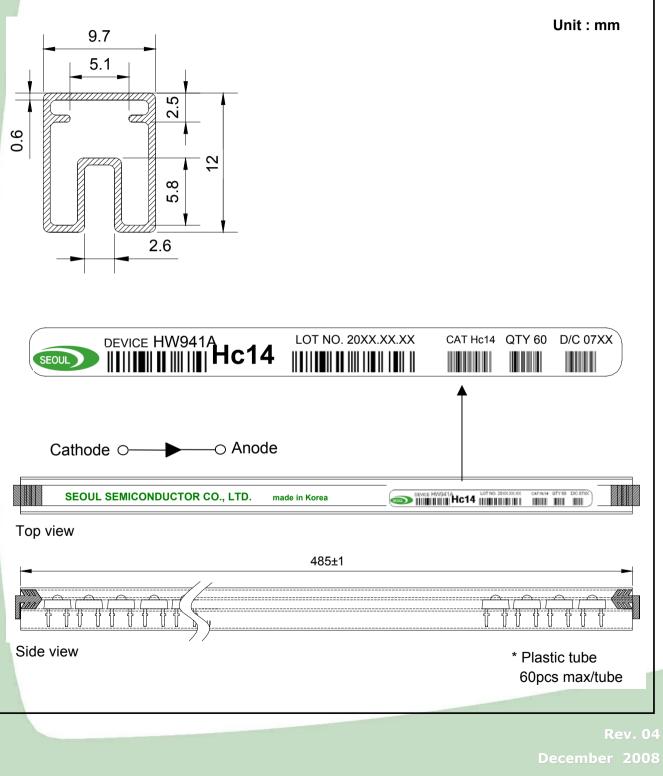
Color Rank
@ <i>I_F</i> = 30mA
а
b1
b2
c1
c2
d

Forward Voltage (V) @ <i>I_F</i> = 30mA					
Bin Code	Min.	Max.			
1	2.8	3.0			
2	3.0	3.2			
3	3.2	3.4			
4	3.4	3.6			
5	3.6	3.8			
6	3.8	4.0			
7	4.0	4.2			

Available ranks

Rev. 04 December 2008 www.ZLED.com

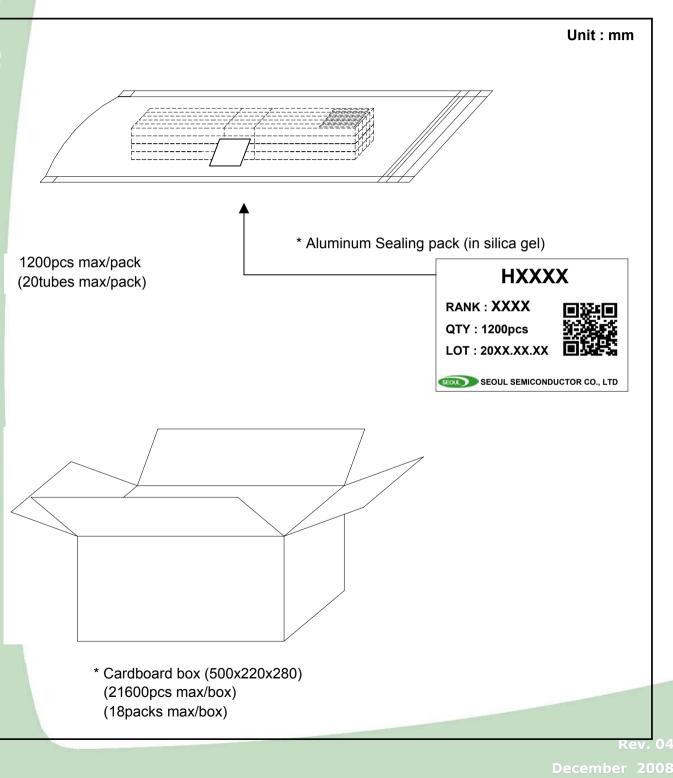
9. Packing



SEOUL SEMICONDUCTOR

SEOUL

9. Packing



Document No. : SSC-QP-7-07-24 (Rev.00)

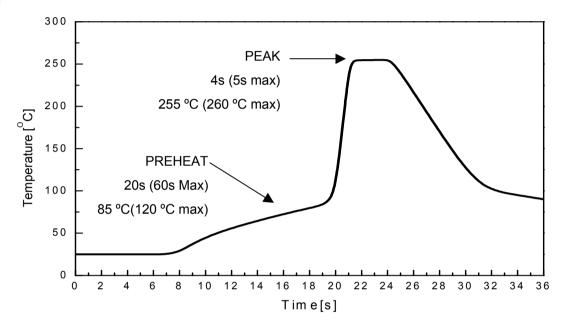


SEOUL

1) Recommended Wave Soldering Conditions / Profile

- Preliminary heating to be at 85°C(120 °C max) for 20 seconds(60 seconds max).
- Soldering heat to be at 255 °C (260°C max) for 4 seconds (5 seconds max.)

Soak time above 200 °C is 5 seconds



- 2) Hand Soldering conditions
- Not more than 3 seconds at max. 350°C, under Soldering iron.
- 3) Caution
- Leadframes are silver plated copper alloy. This substance has a low thermal coefficient (easily conducts heat)
- No closer than 1.5mm from the base of the stopper.
- The LEDs must not be repositioned after soldering.
- Do not apply any stress to the lead particularly when heat.

Note : In case the soldered products are reused in soldering process, we don't guarantee the products.

Rev. 04 December 2008 www.ZLED.com

SEOUL SEMICONDUCTOR

SEOUL

11. Precaution for use

1) Storage

Before opening the package

Avoid the absorption of moisture, we recommended to store High Flux LEDs in a dry box(or desiccator) with a desiccant. Otherwise, store them in the following environment: Temperature : $5^{\circ}C \sim 30^{\circ}C$ Humidity : 50% max.

- After opening the package
 - a. Soldering should be done right after opening the package(within 24Hrs).
 - b. Keeping of a fraction
 - Sealing
 - Temperature : 5 ~ 40 $^\circ\!\!\mathbb{C}$, Humidity : less than 30%
 - c. If the package has been opened more than 1week or the color of desiccant changes, Components should be dried for 10-12hr at $60\pm5\,{}^\circ\!C$
- Any mechanical force or any excess vibration shall not be accepted to apply during cooling process to normal temp. after soldering.
- Avoid quick cooling
- Lead frames are silver plated copper alloy. The silver plate surface may be affected by environments which contains corrosive substances. Please avoid conditions which may cause the LEDs to corrode, tarnish or discolor.
- 2) Static Electricity
- Static Electricity and surge voltage damage the LEDs. So it is recommended that a wrist band or an anti-electrostatic glove be used when handling the LEDs.
- All devices, equipment and machinery must be properly grounded.
 It is recommended precautions be taken against surge voltage to the equipment that mounts the LEDs.
- 3) Heat Generation
- Thermal is one of the important parameter to design the end product. Please consider the heat generation of the LEDs.
- The operating current should be decided after considering the ambient maximum temperature of LEDs.

Rev. 04 December 2008 www.ZLED.com

Document No. : SSC-QP-7-07-24 (Rev.00)

SEOUL SEMICONDUCTOR

SEOUL

4) Others

- The color of the LEDs is changed slightly an operating current and thermal.
- Anti radioactive ray design is not considered for the products listed here.
- Gallium arsenide is used in some of the products listed in this publication. These products are dangerous if they are burned or smashed in the process of disposal. It is also dangerous to drink the liquid or inhale the gas generated by such products when chemically disposed.
- This device should not be used in any type of fluid such as water, oil, organic solvent and etc. When washing is required, IPA(Isopropyl Alcohol) should be used.
- When the LEDs are illuminating, operating current should be decided after considering the junction temperature.

Cf.) Please refer Ambient temperature vs. Forward Current graph on page 5

• The appearance and specifications of the product may be modified for improvement without notice.



12. Reliability Test Item and Condition

ltem	Condition	Note	Failures
Life Test	$T_a = RT, I_F = 30 mA$	1000hrs	0/22
High Temperature Operatir	g $T_a = 85^{\circ}\text{C}, \ I_F = 10\text{mA}$	1000hrs	0/22
Low Temperature Operatin	g $T_a = -30^{\circ}\text{C}, \ I_F = 30\text{mA}$	1000hrs	0/22
Thermal Shock	T_a = -40°C (15min) ~ 100° (15min) (Transfer time : 10sec, 1Cycle = 30min)	100 cycles	0/40
Resistance to soldering He	at $T_{\rm s} = 255 \pm 5^{\circ}$ C, $t = 4 \pm 1$ sec	1 time	0/22
ESD (Human Body Model)	1kV, 1.5kΩ ; 100pF	1 time	0/22
High Temperature Storage	$T_a = 100^{\circ} \text{C}$	1000hrs	0/22
Low Temperature Storage	$T_a = -40^{\circ}{ m C}$	1000hrs	0/22
Temperature Humidity Storage	<i>T_a</i> = 85°C, <i>RH</i> = 85%	1000hrs	0/22
Temperature Humidity Operating	<i>T_a</i> = 85°C, <i>RH</i> = 85%, <i>I_F</i> = 10mA	500hrs	0/22

< Judging Criteria For Reliability Tests >

V _F	USL ^[1] X 1.2
I _R	USL X 2.0
Φ_V	LSL ^[2] X 0.7

Notes :

[1] USL : Upper Standard Level [2] LSL : Lower Standard Level.

> Rev. 04 December 2008 www.ZLED.com